

Material Composition Specification

SOT-963 Case



Device average mass **1.195 mg**
 Fluctuation margin **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	2.51%	0.03	Si	7440-21-3	2.51%	0.03	25,109
bond wire	gold	1.26%	0.015	Au	7440-57-5	1.26%	0.015	12,554
leadframe	Cu alloy	42.87%	0.5122	Cu	7440-50-8	41.93%	0.501	419,317
				Fe	7439-89-6	0.92%	0.011	9,207
				P	7723-14-0	0.01%	0.0001	84
				Zn	7440-66-6	0.01%	0.0001	84
die attach	silver epoxy	1.17%	0.014	Ag	7440-22-4	1.0%	0.012	10,044
				resin filler	Proprietary	0.17%	0.002	1,674
encapsulation	EMC	50.8%	0.607	amorphous silica	7631-86-9	49.21%	0.588	492,133
				epoxy resin	Proprietary	1.51%	0.018	15,065
				carbon	1333-86-4	0.08%	0.001	837
plating	Ni/Pd/Au	1.39%	0.0166	Ni	7440-02-0	1.34%	0.016	13,391
				Pd	7440-05-3	0.01%	0.0001	84
				Au	7440-57-5	0.04%	0.0005	418

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

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